

September 2010

DB3-DB3TG 150mW Bi-directional Trigger Diodes

Features

- V_{BO}: 32V Version
- Low break-over current
- DO-35 package (JEDEC)
- · Hermetically sealed glass
- · Compression bonded construction
- All external surfaces are corrosion resistant and terminals are readily solderable
- RoHS compliant
- High reliability glass passivation insuring parameter stability and protection against junction contamination.
- Terminal: Pure tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed: 260C/10 seconds



DO-35

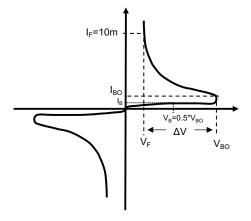
Absolute Maximum Ratings and Electrical Characteristics

Symbol	Parameter		Value		Units
Symbol			DB3	DB3TG	Units
V _{BO}	Break-over Voltage @ C=22nF	Min.	28	30	V
		Тур.	32	32	V
		Max.	36	34	V
±V _{BO}	Break-over Voltage Symmetry @ C=22nF	Max.	±3	±2	V
I _{BO}	Break-over Current @ C=22nF	Max.	100	15	μΑ
ΔV	Dynamic Break-over Voltage @ I _{BO} to I _F =10mA	Min.	5	9	V
I _B	Leakage Current @ V _B =0.5V _{BO} (Max.)	Max.	10		μА
Vo	Output Voltage *see diagram 1	Min.	5		V
P _D	Power Dissipation	150		mW	
I _{FRM}	Repetitive Peak Forward Current, Pulse Width=20	2		А	
$R_{\theta ja}$	Typical Thermal Resistance, Junction to Ambient (Note1)		400		°C/W
T _{J,} T _{STG}	Junction and Storage Temperature Range	-40 to +125		°C	

^{*} Rating at 25°C ambient temperature unless otherwise specified.

^{*} Notes: 1. Valid provided that electrodes are kept at ambient temperature

Typical Performance Characteristics



 $\begin{array}{ll} \textbf{V}_{BO} & : Break-Over \ Voltage \\ \textbf{I}_{BO} & : Break-Over \ Current \\ \textbf{\Delta V} & : Dynamic \ Breakover \ Voltage \\ \textbf{I}_{B} & : Leakage \ Current \ at \ V_{B} = 0.5^* V_{BO} \end{array}$

V_F : Voltage at Current I_F=10mA

Diagram 1 : Test circuit

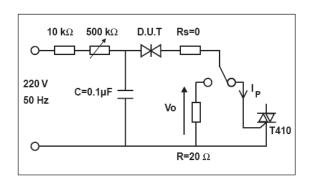


Figure 1. Admissible Power Dissipation Curve

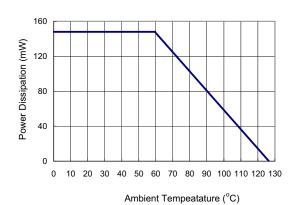


Figure 2. Relative Variation of VBO versus Junction Temperature

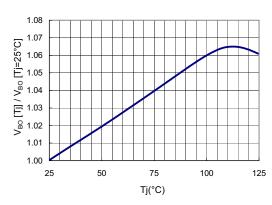
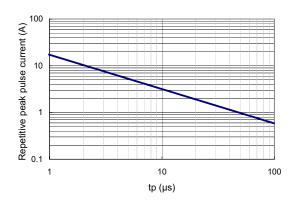
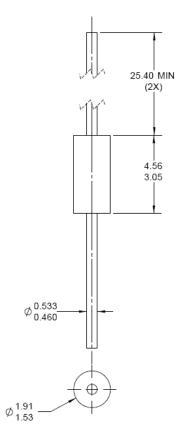


Figure 3. Repetitive Peak Pulse Current versus Pulse Duration (maximum values)



Physical Dimensions

DO-35



NOTES: UNLESS OTHERWISE SPECIFIED

- PACKAGE STANDARD REFERENCE:
 JEDEC DO-204, VARIATION AH.
 HERMETICALLY SEALED GLASS PACKAGE.
 PACKAGE WEIGHT IS 0.137 GRAM.
 D ALL DIMENSIONS ARE IN MILLIMETERS.
 DRAWING FILE NAME: DO35AREV02

Dimensions in Millimeters





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